CONFIGURATION:-

Valid ATP-document X1400E
1: Software release Twinscan Sw rel. 4.1.0
Power 400 Volt
Wafer size 300 mm
Wafer type Flat
Laser MODEL CYMER XLA 160+/165 (45W)
Laser type Cymer Laser
OIU/Reticle-/Waf.aux.port Left Configuration
Machine Location Customer-site
MES machine type XT1400E
FOUP mechan. door sensor No
PPD IRIS (CSR) No
CSR's for XT1400E various CSR 8004
CSR: AT Multilingual UI No
Pellicle Safeguard (CSR) No
CSR: LS M2M P2P No
WH Carrier Interface 25 Wafer Open Cassette kit
Wafer Track Interface TEL Cleantrack Lithius/200
Mark sensor (WH opt.pre-align) Yes
Integrated Reticle Library Yes
IRIS-6 Inch Reticles Twinscan ATASF ASF: IRIS-XT with PPD2_1
Reticle CIDRW (Tag Reader) No
FOUP Lockout system No
Second Laser paddle Yes
ASF: MDL View CUST Site View
24 char Reticle Barcode Reader Yes
Reorder Lot Service No
Universal Prealignment No
Recipe Creator Recipe Creator "Light"
Automated Reticle Transport No
WH PEP option (XT1400E), 200mm PEP-Upgraded tpt 200mm, 180wph
EFESE No
Proximity matching (CSR!) Yes (check additional text)
AGILE No
CSR: L1L7 Type_1 No
ASF: LS Area Extension No
Chemical Sampling ports No
ExpoSure Yes
ASF: LS Spot Coverage Yes
Aerial-P / Polarization No
BAM: Bandwidth Analysis Module No
InformPro/SystemPerf.Ind.Focus No
Equipment Constants No
Image Tuner No
2D Barcode Reader No
ASF: Echuck Flatness Qualific. No
Wait Watcher No
Reticle Streaming Yes (Reticle Streaming)
CSR: Use UIP Ranges No

Gridmapper Yes (LCP needed @ Fab)
SpotLess Yes (NOT XT:1700Fi, XT:19x0xi)
Chuck Dedication Yes
Active Contrast Control No
TOP PACKAGES Standard (TOP 2)
ASF: Enh TPT Reticle Align Ext Yes
ASF: Intel XT:1400E/F No
2DE Grid Calibration Yes
Gas Life Extension GLX YES (purchased)
Dosemapper Standard (LCP needed @Fab)
CCD Option No
Sourcing Level LPA Local Sourcing

Standard Specification Performance for ASML XT1400E:-

CATEGORY ITEMS SPEC
FULL ACCEPTANCE TEST XT1400E
1. DynamicPerformance 1.1 MA X & Y (mean+3sig) [nm] ≤ 1.7
1.2 MSD X& Y (max of mean per field) [nm] ≤ 6.50
2 Overlay Performance 2.1 Stage repeatability [nm] ≤ 4.0
2.2 Single machine overlay (Setting 1, chuck A to chuck B) nm ≤ 8
3. Productivity 3.1 Wafer throughput: 125 exposures, 30mJ/cm2
16x32mm(dose30mJ/cm2),Setting1[w/h] ≥ 122
3.3 Reticle exchange time
setting 1 --> setting 2 [s] ≤ 13
3.4 Lot overhead (incl. Reticle Exchange)
setting 1 --> setting 2 [s] ≤ 13
4. Intensity 4.1Illumination intensity,11 scans in 26mm Setting 1[mW/cm2] ≥ 2260*
5. Projection Lens 5.1 RMS Z5-Z37 [nm] ≤ 1.7
5.2 RMS spherical [nm] ≤ 1.0
5.3 RMS coma [nm] ≤ 0.9
5.4 RMS astigmatism [nm] ≤ 0.9
5.5 RMS 3-foil [nm] ≤ 0.9
5.6 Non correctable error after correction for reticle error Setting1[nm] ≤ 7.0
5.7 Image plane deviation at 65nm, Setting 1 [nm] ≤ 43
5.8 Astigmatism at 65nm, Setting 1 [nm] ≤ 25
5.9 Long range straylight [SAMOS %] ≤ 0.9
5.10 Short range straylight [SAMOS %] ≤ 1.2
6. Dose control 5.1 Dose system performance, Setting 1 [%] ≤ 1.2
5.2 Integrated slit uniformity, Setting 1 [%] ≤ 0.30
5.3 Integrated scan uniformity, Setting 1 [%] ≤ 0.2
5.4 Dose reproducibility [%] ≤ 0.25
5.5 Dose accuracy, setting1 [%] ± 1.0
5.6 Dose stability, 3day [%] ≤ 0.5
6. Pupil Verification 6.1 Ellipticity, Setting1 [|mean|] ≤ 2.0
6.2 Sigma variation, Setting1 [range] ≤ 0.010
7. Focus and Leveling 7.1 Wafer map repeatability (99.7%) [nm] ≤ 10
7.2 Leveling verification
Chuck to chuck focus difference [nm] ≤ 10
Full focus uniformity [nm] ≤ 50